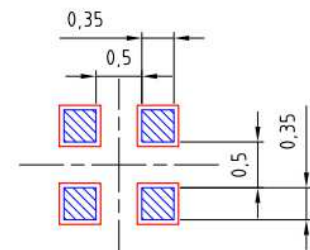
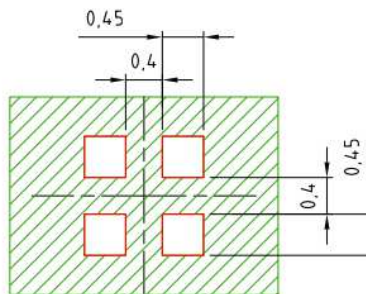
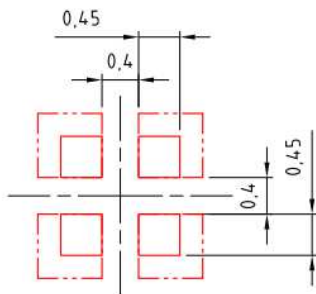


Gewicht / Approx. weight:

1.38 mg

Empfohlenes Lötpad Design ^{7) Seite 29}
Recommended Solder Pad ^{7) page 29}

Reflow Löten
 Reflow Soldering



 foot print  Cu area

 solder resist

 solder stencil

Component Location on Pad

